

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions, listing, of claims in the specification.

LISTING OF CLAIMS:

Claim 1 (original) A chip adhesive adhered to a stacked packaging structure between two adjacent chips, and the chip adhesive includes a plurality of stuff particles to keep the chip adhesive with a predetermined thickness.

Claim 2 (original) The chip adhesive of Claim 1 can further control the thickness through suitably selecting a type of the stuff particle.

Claim 3 (original) the chip adhesive of Claim 1 can further control the thickness through suitably selecting a quantity of the stuff particle.

Claims 4-5 (canceled).

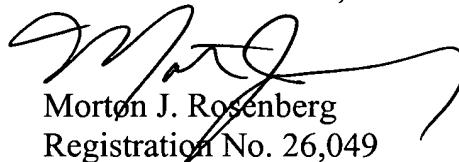
MR1035-1345  
Appln. No. 10/720,524  
Reply to Office Action dated 8/30/2005

This case has been reviewed and analyzed in view of the Official Action dated 30 August 2005. In the Official Action, the Examiner has found two inventions, namely, Group I directed to Claims 4 and 5 drawn to a stacked packaging structure; and Group II directed to Claims 1-3 drawn to a chip adhesive. The Examiner has required that Applicant chose Group I or Group II for further prosecution in this case.

By this Amendment and Response, Applicant has canceled Claims 4-5 and elects Claim 1-3 for further prosecution.

It is now believed that the subject patent application has been placed in condition for examination and such action is respectfully requested.

Respectfully submitted,  
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